



Structural Analyses and Designs for Flexible/Stretchable Electronics

Guest Editor:

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Message from the Guest Editor

Flexible and stretchable electronics represent a class of promising technology that involves stretchable/bendable/twistable components such that unprecedented properties are achieved over conventional rigid/brittle semiconductor-based electronics.

This Special Issue seeks contributions on different aspects of flexible and stretchable electronics, with a focus on mechanical analyses and structural designs toward various component-level or device-level applications. Research papers and review articles are both welcome. The topics include but are not limited to:

- *Mechanical analysis methods of flexible/stretchable electronics on either device-level or component-level;

- *Structural optimization and design theories toward providing better related performance;

- *Experimental studies on various properties of flexible/stretchable electronics;

- *Novel flexible/stretchable structures with extraordinary mechanical or electrical properties;

- *Designs of materials, structures, and components for special application scenarios, such as bioelectronics and implantable electronics.





Editor-in-Chief

Message from the Editor-in-Chief

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